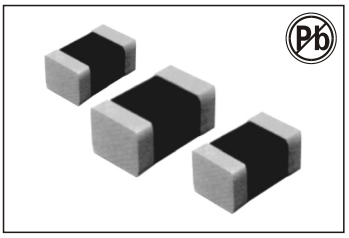
SURFACE–MOUNT MULTI–LAYER CHIP BEADS

SBL 2012,3216 SERIES



FEATURES:

- Multilayer structure
- Closed magnetic circuit
- Avoids crosstalk
- Excellent magnetic shield
- Excellent solderability
- High reliability
- EMI/RFI suppression
- 20%impedance tolerance

OPTIONS:

- Packaging:Tape & Reel is standard (Qty's:2000pcs)
  Bulk packaging available for smaller quantities
- Impedance:Optional values available

COMMON APPLICATIONS:

- Cellular Phones
- Mobil Radios
- Cordless Telephones
- Modems
- Global Positioning Systems
- Wireless Communications Equipment
- Network Systems
- Computer Products

ELECTRICAL CHARACTERISTICS:

Part Number	IMPEDANCE Ω AT 100 MHz	DCR (Ω) Max	IDC Max mA	Part Number	IMPEDANCE (Ω) AT 100 MHz	DCR (Ω) Max	IDC Max mA
SBL2012A070H	7	0.20	600	SBL3216A700H	70	0.30	400
SBL2012A110H	11	0.20	600	SBL3216A800H	80	0.30	300
SBL2012A190H	19	0.20	600	SBL3216A101H	100	0.30	300
SBL2012A260H	26	0.20	400	SBL3216A121H	120	0.30	300
SBL2012A310H	31	0.20	400	SBL3216A151H	150	0.30	300
SBL2012A360H	36	0.20	400	SBL3216A181H	180	0.35	300
SBL2012A600L	60	0.25	400	SBL3216A221H	220	0.30	300
SBL2012A700L	70	0.25	400	SBL3216A301H	300	0.30	300
SBL2012A800L	80	0.25	400	SBL3216A501H	500	0.30	200
SBL2012A101L	100	0.25	400	SBL3216A601H	600	0.30	200
SBL2012A121L	120	0.25	300	SBL3216A801H	800	0.30	200
SBL2012A151L	150	0.25	300	SBL3216A102H	1000	0.30	200
SBL2012A181L	180	0.25	300	SBL3216A122H	1200	0.50	100
SBL2012A221H	220	0.25	300	SBL3216A152H	1500	0.60	100
SBL2012A301H	300	0.25	300	SBL3216A202L	2000	0.60	100
SBL2012A501H	500	0.35	200	SBL3216A252L	2500	0.80	100
SBL2012A601H	600	0.40	200	SBL3216A302L	3000	1.00	80
SBL2012A801H	800	0.40	150				
SBL2012A102H	1000	0.45	100				
SBL2012A122H	1200	0.06	100				
SBL2012A152H	1500	0.80	100				
SBL2012A202H	2000	0.90	50				
SBL2012A222H	2200	1.00	50				
SBL2012A252H	2500	1.20	50				
SBL2012A302H	3000	1.40	50				
SBL3216A190H	19	0.20	500				
SBL3216A260H	26	0.20	500				
SBL3216A310H	31	0.30	500				
SBL3210A600H	60	0.30	400				

Note:1. K=±10%,M=±20%

TECHNICAL INFORMATION

- Testing:Impedance vs.Frequency:HP 4195A
- Solderability:90% of the terminal electrode shall be covered
  Preheat:@ 260℃±5℃ for 60 seconds
  Flux:Rosin,Dip for 10 seconds ±1 second
- Thermal Shock:Impedance shall be within ±20% of initial value when temperature is –25℃ and +85℃ for 30 minutes for each 50 cycles
- Operating Temperature:–25℃ to +85℃
- Storage Temperature:–25℃ to +85℃

Note:All specifications subject to change without notice.

PHYSICAL CHARACTERISTICS

(Refer to Size Chart Page 4)